

ULTEM™ RESIN 4211

REGION ASIA

DESCRIPTION

20% Glass fiber filled and PTFE filled, standard flow Polyetherimide (Tg 217C). ECO Conforming.

TYPICAL PROPERTY VALUES

Revision 20180905

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, yld, Type I, 5 mm/min	129	MPa	ASTM D 638
Tensile Strain, brk, Type I, 5 mm/min	3	%	ASTM D 638
Flexural Stress, brk, 2.6 mm/min, 100 mm span	193	MPa	ASTM D 790
Flexural Modulus, 2.6 mm/min, 100 mm span	7100	MPa	ASTM D 790
IMPACT			
Izod Impact, Reverse Notched, 3.2 mm	437	J/m	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 6.4 mm, unannealed	212	°C	ASTM D 648
PHYSICAL			
Specific Gravity	1.48	-	ASTM D 792
Melt Flow Rate, 337°C/6.6 kgf	10.3	g/10 min	ASTM D 1238
INJECTION MOLDING			
Drying Temperature	135	°C	
Drying Time	4 – 6	hrs	
Drying Time (Cumulative)	10	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	350 – 370	°C	
Nozzle Temperature	350 – 370	°C	
Front - Zone 3 Temperature	350 – 370	°C	
Middle - Zone 2 Temperature	345 – 365	°C	
Rear - Zone 1 Temperature	340 – 360	°C	
Mold Temperature	135 – 165	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	40 – 70	rpm	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.025 – 0.076	mm	

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.